ABSTRACT

It is an object of the present invention to provide a power module whose production cost can be kept low. A power module (5, 5A, 5B, 5C, 5D, 5E, 5F) comprises a power semiconductor (53a), a non-power semiconductor (53b), one resin substrate (51, 51A, 51B, 51C, 51D, 51E, 51F), and cooling means (59, 59A). The power semiconductor and the non-power semiconductor configure a power supply circuit for performing power conversion. Both the power semiconductor and the non-power semiconductor are mounted on the resin substrate. The cooling means is disposed in order to cool the power semiconductor.